

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	158	("204" "205").clas. and organic adj. contaminant\$ and (electroplating\$ electrodeposition\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:57
L3	48	("204" "205").clas. and oxide with acid adj. (etching\$ cleaning\$) and (electroplating\$ electrodeposition\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 12:39
L4	38	("204" "205").clas. and oxide with acid adj. (etching\$ cleaning\$) and (electroplating\$ electrodeposition\$) and copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 12:39
L5	29	("204" "205").clas. and oxide with acid adj. (etching\$ cleaning\$) and (electroplating\$ electrodeposition\$) same copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 12:41
L6	62	205/210.cds. and acid with oxide and copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 12:51
L7	45138	KURIYAMA\$-F\$.in. KUMI\$-F\$.in. SAITO\$-N\$.in. TAKEMURA\$-T\$.in. KIMURA\$-M\$.in. TAKEDA\$-S\$.in. GUO\$-Y\$.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 13:04
L8	7	L7 and ozone.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 13:05
L9	16	("20020092542"   "20030003320"   "20030092261"   "20030140949"   "4505786"   "4898650"   "5215593"   "6136163").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 13:16

L10	5	L9 and ozone	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 13:17
S1	1148	(semiconductor wafer microfeature microelectronic) with (ozone ozonated) adj water	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:09
S2	12	S1 and ("204" "205"). clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:09
S3	5	"07161672"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:11
S4	20	(semiconductor wafer microfeature microelectronic) with (electroplat\$ electrodeposit\$ electrocoat\$) and ("204" "205").clas. and ((pre adj clean) preclean)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:15
S5	59	(semiconductor wafer microfeature microelectronic) same (electroplat\$ electrodeposit\$ electrocoat\$) and ("204" "205").clas. and ((pre adj clean) preclean)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:23
S6	17	(semiconductor wafer microfeature microelectronic) same (electroplat\$ electrodeposit\$ electrocoat\$) and ("204" "205").clas. and (pre adj rinse)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:29

S7	2	(semiconductor wafer microfeature microelectronic) with (ozone ozonated) adj water and ("134").clas. and (electroplat\$ electrodeposit\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:31
S8	2	"4911761".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:35
S9	159	(semiconductor wafer microfeature microelectronic) with (ozone ozonated) adj water and ("134").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:35
S10	16	(semiconductor wafer microfeature microelectronic) with (ozone ozonated) adj water with contaminant and ("134").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:36
S11	2	"6136163".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/28 11:38

9/28/08 1:39:07 PM

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